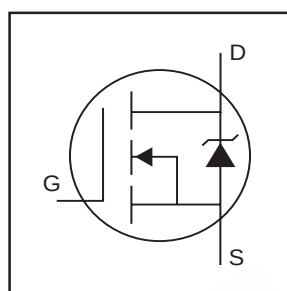


- Advanced Process Technology
- Dynamic dv/dt Rating
- 175°C Operating Temperature
- Fast Switching
- Fully Avalanche Rated

Description

Fifth Generation HEXFETs from International Rectifier utilize advanced processing techniques to achieve the lowest possible on-resistance per silicon area. This benefit, combined with the fast switching speed and ruggedized device design that HEXFET Power MOSFETs are well known for, provides the designer with an extremely efficient device for use in a wide variety of applications.

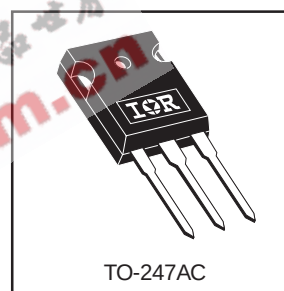
The TO-247 package is preferred for commercial-industrial applications where higher power levels preclude the use of TO-220 devices. The TO-247 is similar but superior to the earlier TO-218 package because of its isolated mounting hole.



$$V_{DS} = 100V$$

$$R_{DS(on)} = 0.052\Omega$$

$$I_D = 33A$$



TO-247AC

Absolute Maximum Ratings

	Parameter	Max.	Units
I_D @ $T_C = 25^\circ C$	Continuous Drain Current, V_{GS} @ 10V⑤	33	A
I_D @ $T_C = 100^\circ C$	Continuous Drain Current, V_{GS} @ 10V⑤	23	
I_{DM}	Pulsed Drain Current ①⑤	110	
P_D @ $T_C = 25^\circ C$	Power Dissipation	140	W
	Linear Derating Factor	0.91	W/°C
V_{GS}	Gate-to-Source Voltage	±20	V
E_{AS}	Single Pulse Avalanche Energy ②⑤	300	mJ
I_{AR}	Avalanche Current①	16	A
E_{AR}	Repetitive Avalanche Energy①	14	mJ
dv/dt	Peak Diode Recovery dv/dt ③⑤	5.0	V/ns
T_J	Operating Junction and	-55 to + 175	°C
T_{STG}	Storage Temperature Range		
	Soldering Temperature, for 10 seconds		
	Mounting torque, 6-32 or M3 screw.	10 lbf•in (1.1N•m)	

Thermal Resistance

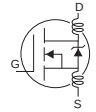
	Parameter	Min.	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case	—	—	1.1	°C/W
$R_{\theta CS}$	Case-to-Sink, Flat, Greased Surface	—	0.24	—	
$R_{\theta JA}$	Junction-to-Ambient	—	—	40	

IRFP140N

International
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Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	100	—	—	V	$V_{GS} = 0V$, $I_D = 250\mu A$
$\Delta V_{(BR)DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	—	0.11	—	V/ $^\circ\text{C}$	Reference to 25°C , $I_D = 1mA$ ⑤
$R_{DS(on)}$	Static Drain-to-Source On-Resistance	—	—	0.052	Ω	$V_{GS} = 10V$, $I_D = 16A$ ④
$V_{GS(th)}$	Gate Threshold Voltage	2.0	—	4.0	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$
g_{fs}	Forward Transconductance	11	—	—	S	$V_{DS} = 50V$, $I_D = 16A$ ⑤
I_{DSS}	Drain-to-Source Leakage Current	—	—	25	μA	$V_{DS} = 100V$, $V_{GS} = 0V$
		—	—	250		$V_{DS} = 80V$, $V_{GS} = 0V$, $T_J = 150^\circ\text{C}$
I_{GSS}	Gate-to-Source Forward Leakage	—	—	100	nA	$V_{GS} = 20V$
	Gate-to-Source Reverse Leakage	—	—	-100		$V_{GS} = -20V$
Q_g	Total Gate Charge	—	—	94	nC	$I_D = 16A$
Q_{gs}	Gate-to-Source Charge	—	—	15		$V_{DS} = 80V$
Q_{gd}	Gate-to-Drain ("Miller") Charge	—	—	43		$V_{GS} = 10V$, See Fig. 6 and 13 ④⑤
$t_{d(on)}$	Turn-On Delay Time	—	8.2	—	ns	$V_{DD} = 50V$
t_r	Rise Time	—	39	—		$I_D = 16A$
$t_{d(off)}$	Turn-Off Delay Time	—	44	—		$R_G = 5.1\Omega$
t_f	Fall Time	—	33	—		$R_D = 3.0\Omega$, See Fig. 10 ④⑤
L_D	Internal Drain Inductance	—	5.0	—	nH	Between lead, 6mm (0.25in.)
L_S	Internal Source Inductance	—	13	—		from package and center of die contact
C_{iss}	Input Capacitance	—	1400	—	pF	$V_{GS} = 0V$
C_{oss}	Output Capacitance	—	330	—		$V_{DS} = 25V$
C_{rss}	Reverse Transfer Capacitance	—	170	—		$f = 1.0MHz$, See Fig. 5⑤



Source-Drain Ratings and Characteristics

	Parameter	Min.	Typ.	Max.	Units	Conditions
I_S	Continuous Source Current (Body Diode)	—	—	33	A	MOSFET symbol showing the integral reverse p-n junction diode.
I_{SM}	Pulsed Source Current (Body Diode) ①⑤	—	—	110		
V_{SD}	Diode Forward Voltage	—	—	1.3	V	$T_J = 25^\circ\text{C}$, $I_S = 16A$, $V_{GS} = 0V$ ④
t_{rr}	Reverse Recovery Time	—	170	250	ns	$T_J = 25^\circ\text{C}$, $I_F = 16A$
Q_{rr}	Reverse Recovery Charge	—	1.1	1.6	μC	$di/dt = 100A/\mu s$ ④⑤

Notes:

① Repetitive rating; pulse width limited by max. junction temperature. (See fig. 11)

② $V_{DD} = 25V$, starting $T_J = 25^\circ\text{C}$, $L = 2.0mH$
 $R_G = 25\Omega$, $I_{AS} = 16A$. (See Figure 12)

③ $I_{SD} \leq 16A$, $di/dt \leq 210A/\mu s$, $V_{DD} \leq V_{(BR)DSS}$,
 $T_J \leq 175^\circ\text{C}$

④ Pulse width $\leq 300\mu s$; duty cycle $\leq 2\%$.

⑤ Uses IRF540N data and test conditions.

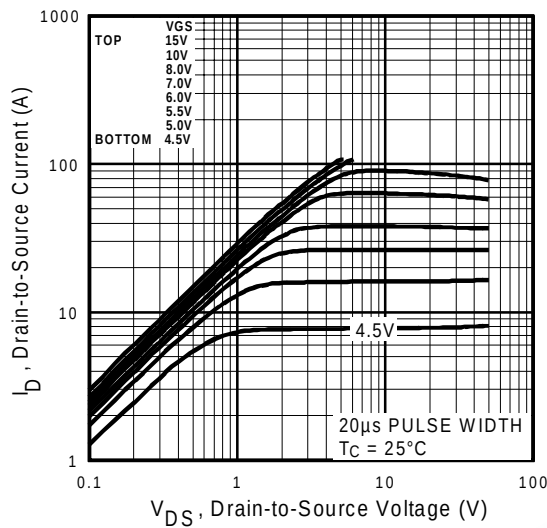


Fig 1. Typical Output Characteristics

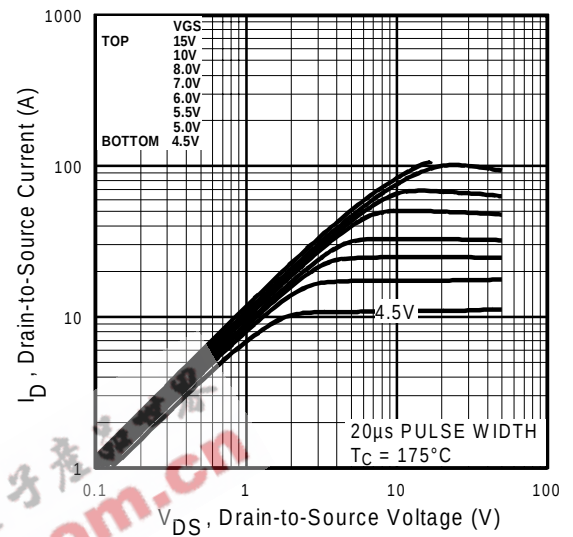


Fig 2. Typical Output Characteristics

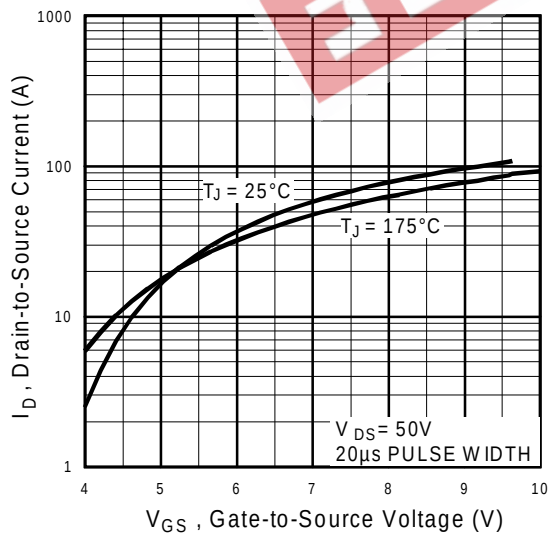


Fig 3. Typical Transfer Characteristics

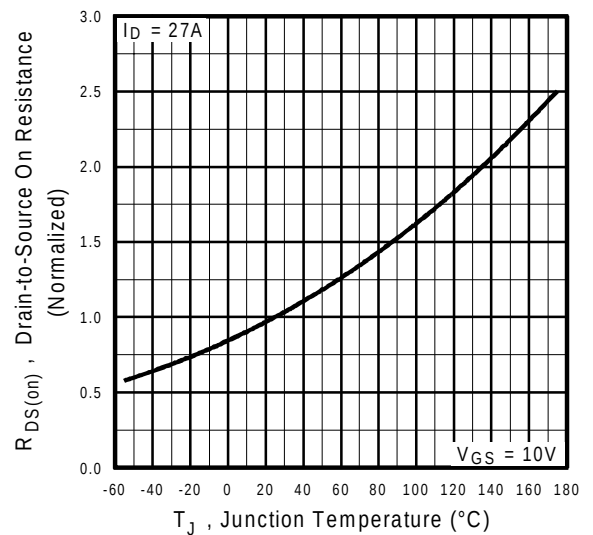


Fig 4. Normalized On-Resistance
Vs. Temperature

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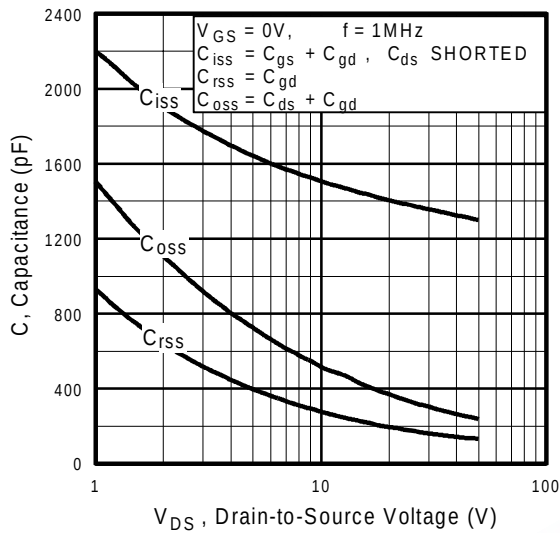


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

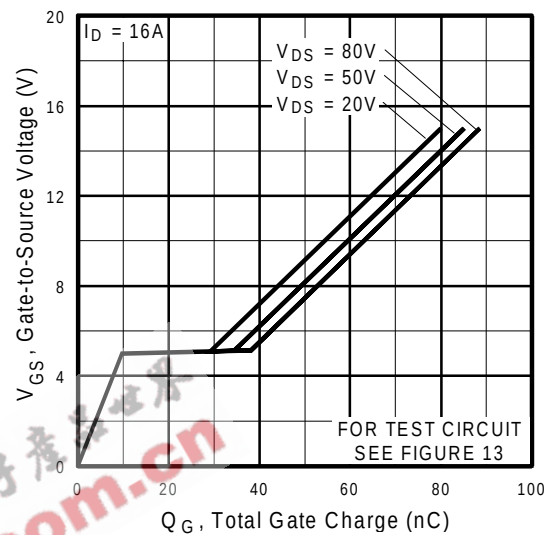


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

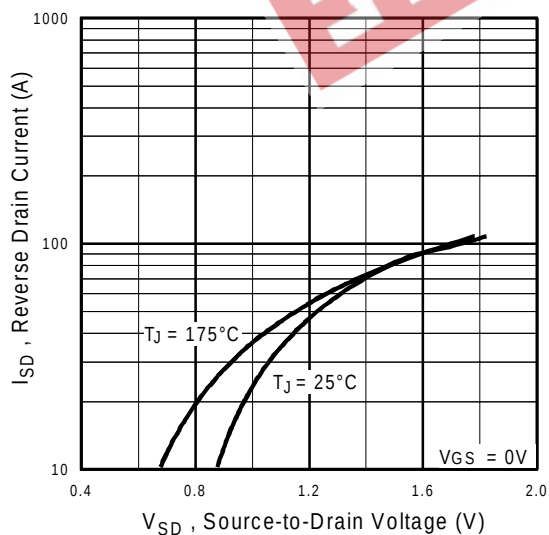


Fig 7. Typical Source-Drain Diode Forward Voltage

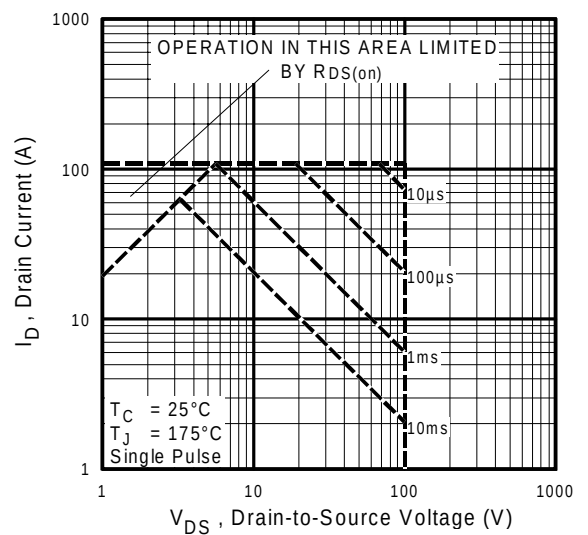


Fig 8. Maximum Safe Operating Area

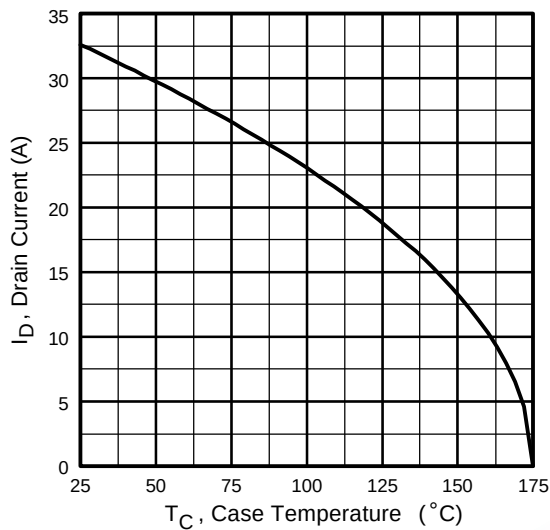


Fig 9. Maximum Drain Current Vs. Case Temperature

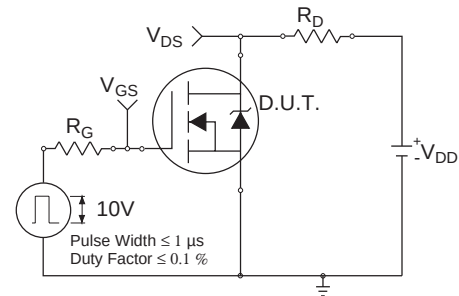


Fig 10a. Switching Time Test Circuit

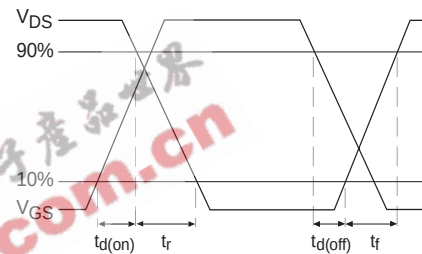


Fig 10b. Switching Time Waveforms

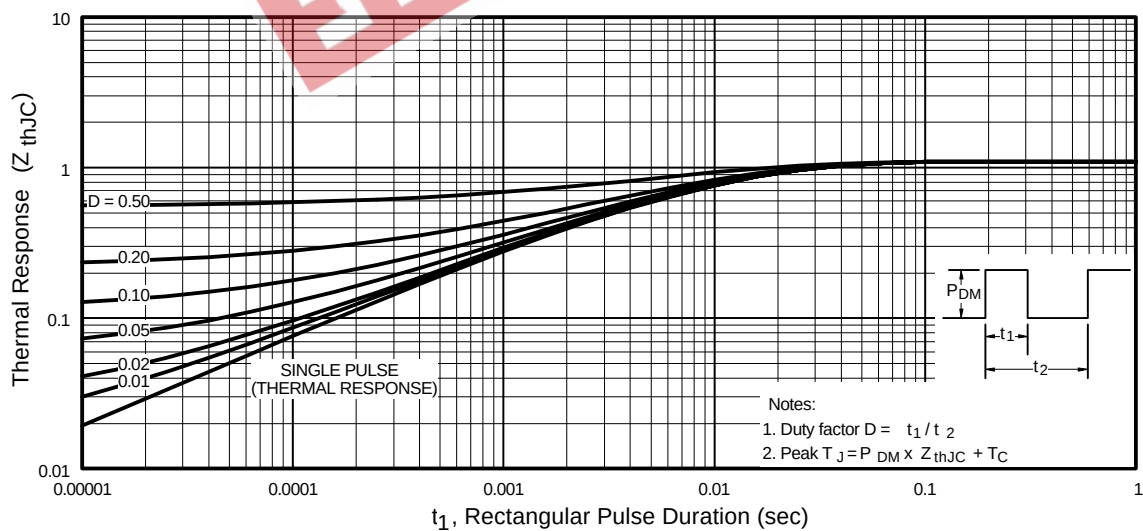


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

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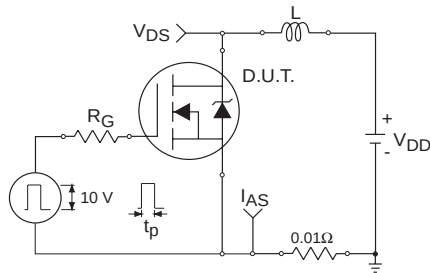


Fig 12a. Unclamped Inductive Test Circuit

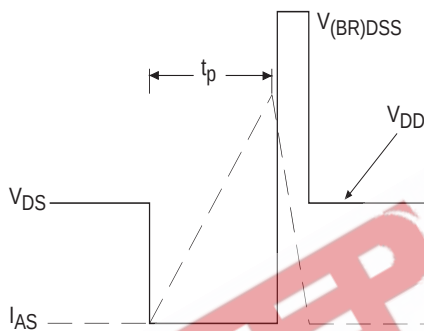


Fig 12b. Unclamped Inductive Waveforms

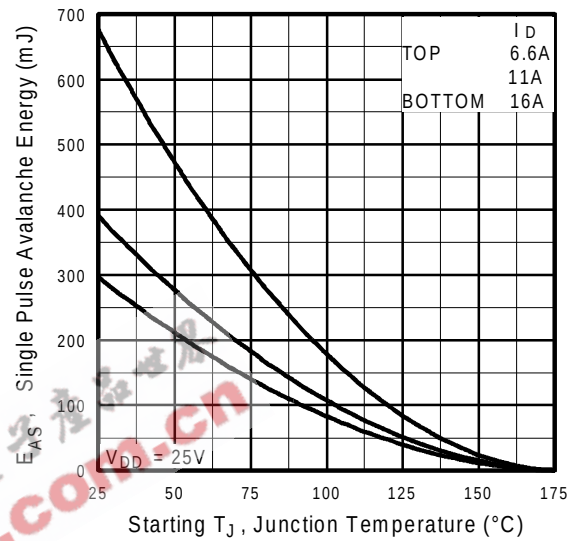


Fig 12c. Maximum Avalanche Energy Vs. Drain Current

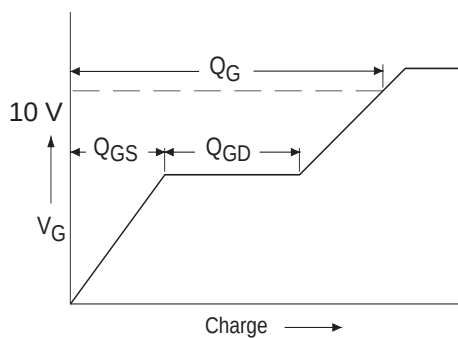


Fig 13a. Basic Gate Charge Waveform

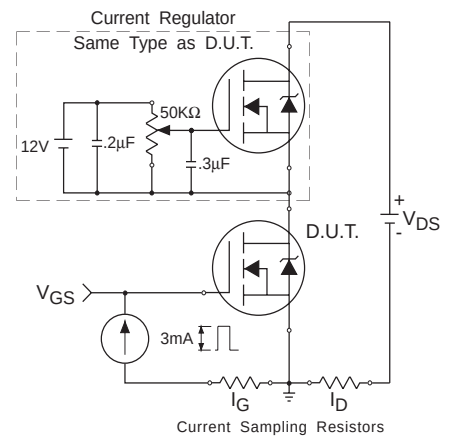


Fig 13b. Gate Charge Test Circuit

Peak Diode Recovery dv/dt Test Circuit

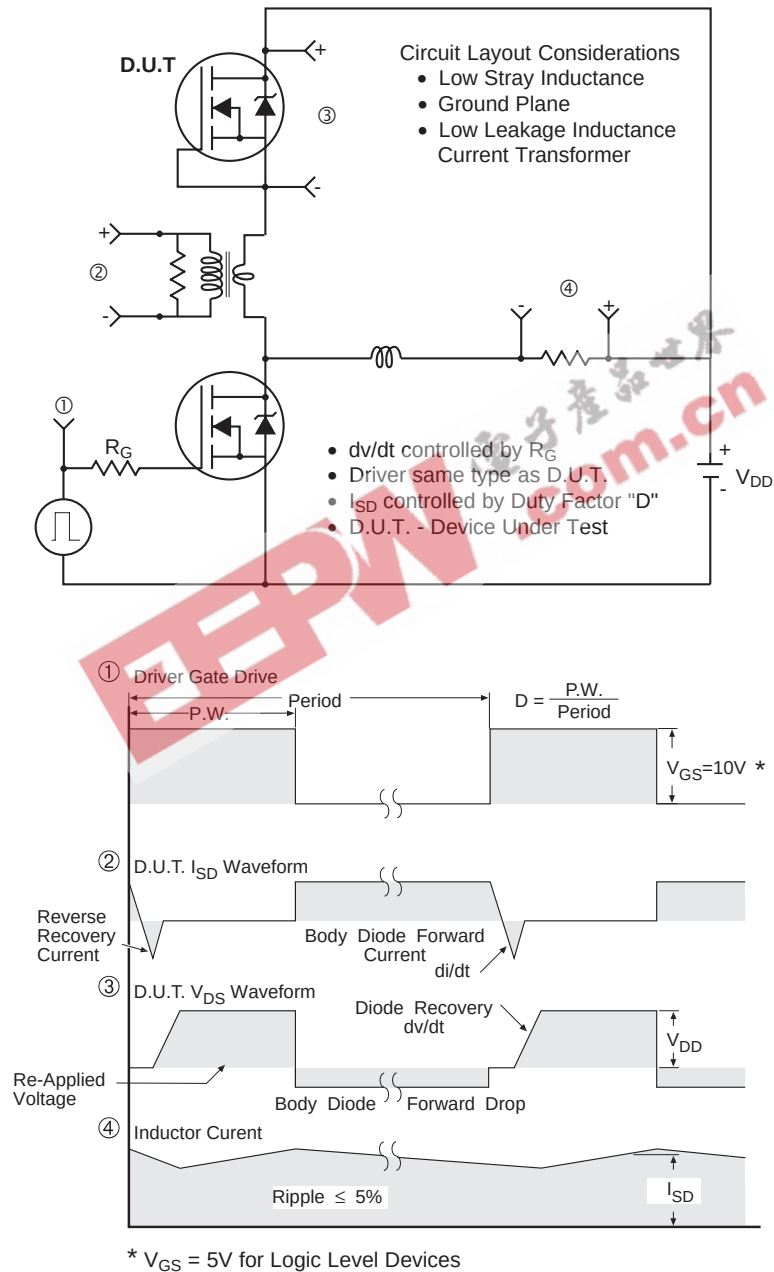


Fig 14. For N-Channel HEXFETS

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TO-247AC Outline

Technical drawing of a 3-pin female D-sub connector. The drawing includes a top view and a side view. The top view shows a rectangular body with three pins (1, 2, 3) and a central mounting hole. Dimensions are given in millimeters (mm) and inches (in). The side view shows the profile of the connector with dimensions for the body height and pin length. A table of material and finish specifications is provided. A large red watermark '电子產品世界.com.cn' is overlaid on the drawing.

Top View Dimensions:

- Overall width: 15.90 (.626)
- Width between pins: 15.30 (.602)
- Pin spacing (1 to 2): 20.30 (.800)
- Pin spacing (2 to 3): 19.70 (.775)
- Pin 1 to center hole: 14.80 (.583)
- Pin 2 to center hole: 14.20 (.559)
- Pin 3 to center hole: 14.80 (.583)
- Pin 1 to pin 2: 2.40 (.094)
- Pin 2 to pin 3: 2.00 (.079)
- Pin 1 to pin 3: 5.45 (.215)
- Pin 1 to pin 2: 2X
- Pin 2 to pin 3: 2X

Side View Dimensions:

- Overall height: 5.30 (.209)
- Height from base to top of body: 4.70 (.185)
- Height from base to top of pin: 2.50 (.089)
- Height from base to top of pin: 1.50 (.059)
- Pin length: 4

Material and Finish Specifications:

Ø 3.65 (.143)	3.55 (.140)	Ø 0.25 (.010)	M	D	B	M
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Notes:

- 1 DIM PER
- 2 COM
- 3 COM
- TO

NOTES:

- 1 DIMENSIONING & TOLERANCING
PER ANSI Y14.5M, 1982.
- 2 CONTROLLING DIMENSION : INCH.
- 3 CONFORMS TO JEDEC OUTLINE
TO-247-AC.

TO-247AC

Diagram illustrating the identification marks on the IRFPE30 MOSFET package:

- INTERNATIONAL RECTIFIER LOGO**: Points to the IOR logo.
- PART NUMBER**: Points to the IRFPE30 text.
- DATE CODE (YYWW)**: Points to the 9302 text. Below this, it specifies: YY = YEAR, WW WEEK.
- ASSEMBLY LOT CODE**: Points to the 3A1Q text.

LEAD ASSIGNMENTS

- 1 - GATE
2 - DRAIN
3 - SOURCE
4 - DRAIN

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<http://www.irf.com/> Data and specifications subject to change without notice. 8/98